

**Product / Package Information**

Package	LFCSP
Body Size (mm)	4X3X0.75
Lead Count	12
Terminal Finish	100 Sn

**Environmental Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	8.14E-03	90.00	900000	40.11		401062
Thermosets	Epoxy Resin	Proprietary	5.79E-04	6.40	64000	2.85		28520
Thermosets	Phenol Resin	Proprietary	2.71E-04	3.00	30000	1.34		13369
Other inorganic materials	Metal Hydroxide	Proprietary	2.71E-05	0.30	3000	0.13		1337
Other inorganic materials	Carbon Black	1333-86-4	2.71E-05	0.30	3000	0.13		1337
Subtotal			9.05 E-03	100.00	1000000	44.56		445625

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Copper & its alloys	Copper	7440-50-8	9.80 E-03	97.50	975000	47.27		472727
Copper & its alloys	Iron	7439-89-6	2.31 E-04	2.35	23500	1.14		11394
Copper & its alloys	Zinc	7440-66-6	1.18 E-05	0.12	1200	0.06		592
Copper & its alloys	Phosphorus	7723-14-0	2.95 E-06	0.03	300	0.01		145
Subtotal			9.84 E-03	100.00	1000000	48.48		484848

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	2.46 E-05	100.0	1000000	0.12		1212

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Tin & its alloys	Tin	7440-31-5	4.64 E-04	100.0	1000000	2.29		22880

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	7.08 E-05	100.0	1000000	0.35		3487

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	7.30 E-04	100.0	1000000	3.60		35955

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Silver	7440-22-4	9.55 E-05	78.50	785000	0.47		4704
Other organic materials	High boiling methacrylate	Proprietary	1.22 E-05	10.00	100000	0.06		599
Other organic materials	Polybutadiene diacrylate	Trade Secret	9.12 E-06	7.50	75000	0.04		449
Other organic materials	Silanamine, 1,1,1-trimethyl-N-(trimethylsilyl)-, hydrolysis	68909-20-6	3.65 E-06	3.00	30000	0.02		180
Other organic materials	Epoxy resin	Trade Secret	6.08 E-07	0.50	5000	0.00		30
Other organic materials	Substituted silane	Proprietary	6.08 E-07	0.50	5000	0.00		30
Subtotal			1.22 E-04	100.0	1000000	0.60		5993

<b>Package Totals</b>			<b>Weight (g)</b> 2.03 E-02			<b>Percentage (%)</b> 100		<b>PPM</b> 1000000
-----------------------	--	--	--------------------------------	--	--	------------------------------	--	-----------------------

Control ID: MS012986APKG5648

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

AHEAD OF WHAT'S POSSIBLE™